SN74AUCH245 OCTAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS SCES420 – JANUARY 2003

- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I_{off} Supports Partial-Power-Down Mode Operation
- Sub 1-V Operable
- Max t_{pd} of 2 ns at 1.8 V
- Low Power Consumption, 20-μA Max I_{CC}
- ±8-mA Output Drive at 1.8 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

RGY PACKAGE (TOP VIEW) V CC DIR 1 20 19 OE 2 A1 A2 3 18 B1 A3 4 17 B2 A4 5 16 **B**3 A5 B4 6 15 B5 A6 7 14 B6 Α7 8 13 B7 A8 9 12 10 11 GND 88

This octal bus transceiver is operational at 0.8-V to 2.7-V V_{CC} , but is designed specifically for 1.65-V to 1.95-V V_{CC} operation.

The SN74AUCH245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

T _A	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AUCH245RGYR	MT245

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



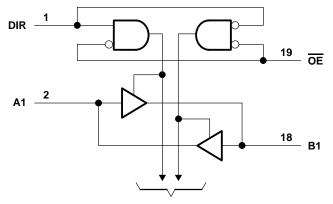
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FUNCTION	
	IADLL

INP	UTS	
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
н	Х	Isolation

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	–0.5 V to 3.6 V
Voltage range applied to any output in the high-impedance or power-off st (see Note 1)	
Output voltage range, V _O (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±20 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2)	37°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-5.



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recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		0.8	2.7	V
		V _{CC} = 0.8 V	VCC		
VIH	High-level input voltage	V _{CC} = 1.1 V to 1.95 V	$0.65 \times V_{CC}$		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 0.8 V		0	
VIL	Low-level input voltage	V _{CC} = 1.1 V to 1.95 V		$0.35 \times V_{CC}$	V
		V _{CC} = 2.3 V to 2.7 V		0.7	
VI	Input voltage		0	3.6	V
	0	Active state	0	V _{CC}	
VO	Output voltage	3-state	0	3.6	V
		V _{CC} = 0.8 V		-0.7	
	High-level output current	V _{CC} = 1.1 V		-3	
IОН		V _{CC} = 1.4 V		-5	mA
••••		V _{CC} = 1.65 V		-8	
		V _{CC} = 2.3 V		-9	
		V _{CC} = 0.8 V		0.7	
		V _{CC} = 1.1 V		3	
IOL	Low-level output current	V _{CC} = 1.4 V		5	mA
		V _{CC} = 1.65 V		8	l
		V _{CC} = 2.3 V		9	
Δt/Δv	Input transition rise or fall rate	·		20	ns/V
Τ _A	Operating free-air temperature		-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vcc	MIN	түр†	MAX	UNIT				
	I _{OH} = -100 μA	0.8 V to 2.7 V	V _{CC} -0.	1						
	$I_{OH} = -0.7 \text{ mA}$	0.8 V		0.55						
	$I_{OH} = -3 \text{ mA}$	1.1 V	0.8							
V _{OH}	$I_{OH} = -5 \text{ mA}$	1.4 V	1			V				
	$I_{OH} = -8 \text{ mA}$	1.65 V	1.2							
	I _{OH} = -9 mA	2.3 V	1.8							
	I _{OL} = 100 μA	0.8 V to 2.7 V			0.2					
	I _{OL} = 0.7 mA	0.8 V		0.25						
	I _{OL} = 3 mA	1.1 V			0.3					
V _{OL}	$I_{OL} = 5 \text{ mA}$	1.4 V			0.4 0.45	V				
	I _{OL} = 8 mA	1.65 V								
	I _{OL} = 9 mA	2.3 V			0.6					
II All inputs	V _I = V _{CC} or GND	0 to 2.7 V			±5	μA				
IBHL‡	V _I = 0.35 V	1.1 V	10							
	V ₁ = 0.47 V	1.4 V	15			1.				
	V _I = 0.57 V	1.65 V	20			μA				
	V ₁ = 0.7 V	2.3 V	40							
	V _I = 0.8 V	1.1 V	-5							
	V ₁ = 0.9 V	1.4 V	-15			μΑ				
I _{BHH} §	V _I = 1.07 V	1.65 V	-20							
	V _I = 1.7 V	2.3 V	-40							
		1.3 V	75							
_		1.6 V	125							
^I BHLO [¶]	$V_{I} = 0$ to V_{CC}	1.95 V	175			μA				
		2.7 V	275							
		1.3 V	-75							
"		1.6 V	-125							
^I BHHO [#]	$V_{I} = 0$ to V_{CC}	1.95 V	-175			μA				
		2.7 V	-275							
l _{off}	$V_{I} \text{ or } V_{O} = 2.7 \text{ V}$	0			±10	μA				
IOZ	$V_{O} = V_{CC}$ or GND	2.7 V			±10	μA				
ICC	$V_{I} = V_{CC}$ or GND, $I_{O} = 0$	0.8 V to 2.7 V			20	μA				
C _i	V _I = V _{CC} or GND	2.5 V		2.5	3	pF				
C _{io}	V _O = V _{CC} or GND	2.5 V		8	8.5	pF				

[†] All typical values are at $T_A = 25^{\circ}C$.

[‡] The bus-hold circuit can sink at least the minimum low sustaining current at VIL max. IBHL should be measured after lowering VIN to GND and then raising it to VIL max.

\$ The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

 \P An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least IBHHO to switch this node from high to low.

|| For I/O ports, the parameter IOZ includes the input leakage current.



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switching characteristics over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 0.8 V	V _{CC} = ± 0.		V _{CC} = ± 0.	= 1.5 V .1 V	•	C = 1.8 0.15 V		V _{CC} = ± 0.		UNIT
	(INPUT)	(001901)	TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
^t pd	A or B	B or A	5	1	3.2	0.6	2	0.5	1	1.7	0.4	1.4	ns	
t _{en}	OE	A or B	9	1.2	4.9	1	3	0.8	1.2	2.4	0.6	1.8	ns	
^t dis	OE	A or B	9.5	1.9	5.7	1.2	4	0.9	1.9	4.1	0.6	2.9	ns	

switching characteristics over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO		C = 1.8 0.15 V		V _{CC} = ± 0.		UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX		
^t pd	A or B	B or A	0.6	1.3	2.2	0.5	1.8	ns	
^t en	OE	A or B	1.1	1.5	3	1.1	2.4	ns	
^t dis	OE	A or B	1.6	2.2	4	0.8	2.6	ns	

operating characteristics, $T_A = 25^{\circ}C$

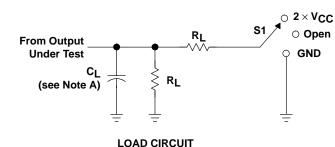
PARAMETER			TEST CONDITIONS	V _{CC} = 0.8 V		V _{CC} = 1.5 V		V _{CC} = 2.5 V	UNIT	
			CONDITIONS	TYP	TYP	TYP	TYP	TYP		
C _{pd}	Power	Outputs enabled	(40 MUL	19	20	21	23	28		
	dissipation capacitance	Outputs disabled	f = 10 MHz	1	1	1	1	1	pF	



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	^t PLH ^{/t} PHL ^t PLZ ^{/t} PZL ^t PHZ ^{/t} PZH	Open 2 × V _{CC} GND	
VCC	CL	RL	v_Δ
0.8 V	15 pF	2 k Ω	0.1 V
1.2 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.5 V \pm 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V \pm 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V \pm 0.2 V	15 pF	2 k Ω	0.15 V
1.8 V \pm 0.15 V	30 pF	1 k Ω	0.15 V

30 pF

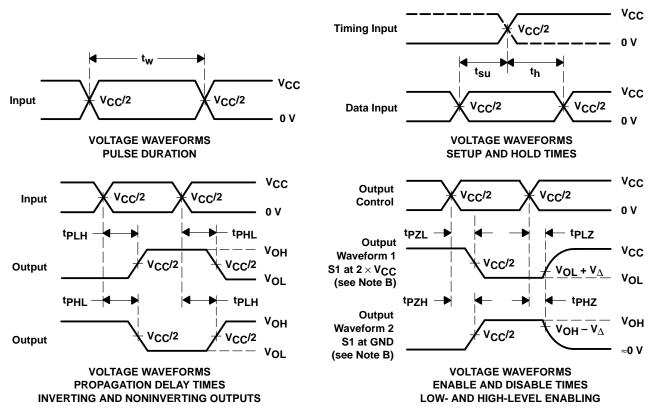
S1

500 Ω

0.15 V

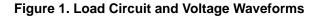
TEST

 $\textbf{2.5 V} \pm \textbf{0.2 V}$



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , slew rate \geq 1 V/ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tPLZ and tPHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	e Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AUCH245RGYR	ACTIVE	VQFN	RGY	20	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	MT245	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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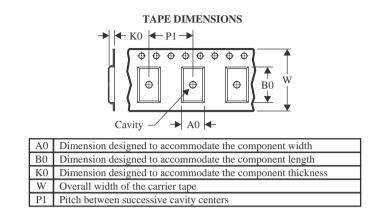


TEXAS

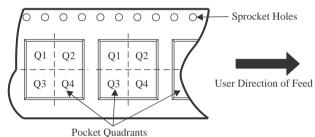
STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



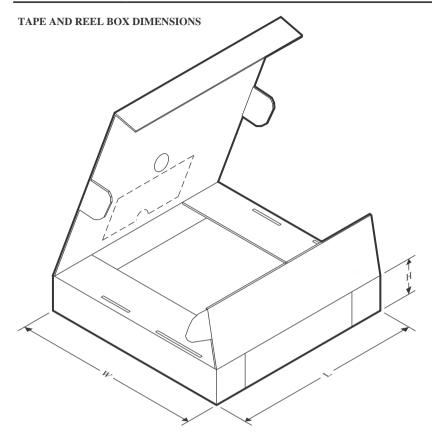
*All dimensions are nominal												
Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUCH245RGYR	VQFN	RGY	20	3000	330.0	12.4	3.8	4.8	1.6	8.0	12.0	Q1



www.ti.com

PACKAGE MATERIALS INFORMATION

3-Jun-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUCH245RGYR	VQFN	RGY	20	3000	356.0	356.0	35.0

GENERIC PACKAGE VIEW

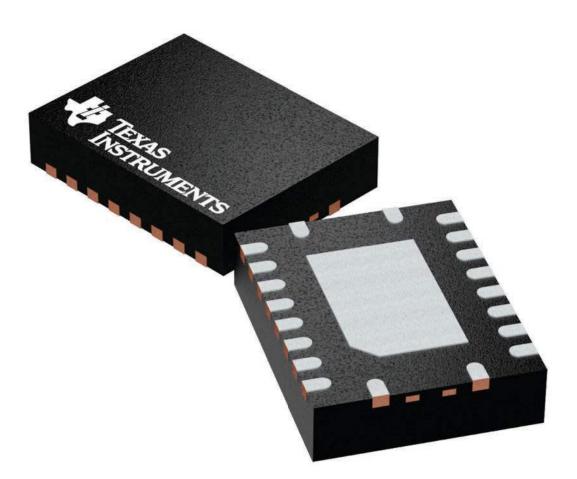
VQFN - 1 mm max height

PLASTIC QUAD FGLATPACK - NO LEAD

3.5 x 4.5, 0.5 mm pitch

RGY 20

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





4225264/A

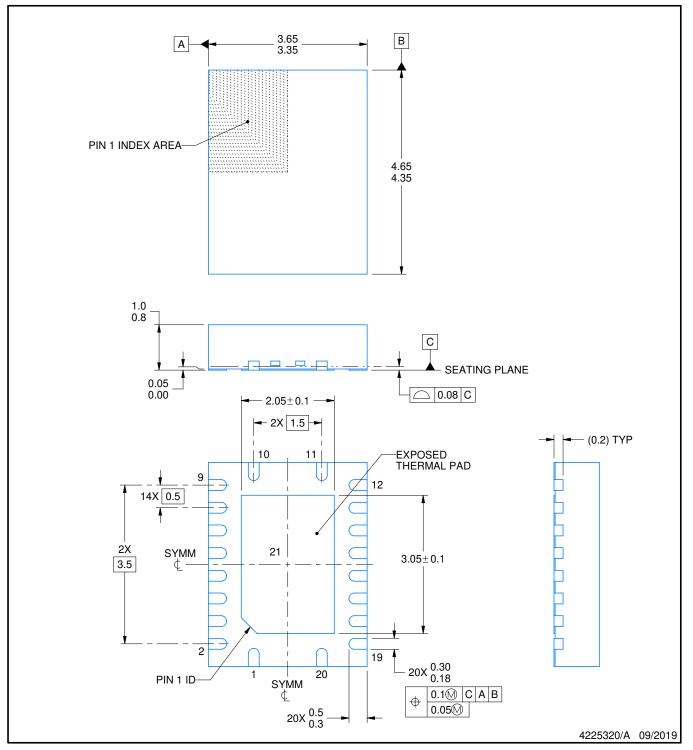
RGY0020A



PACKAGE OUTLINE

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

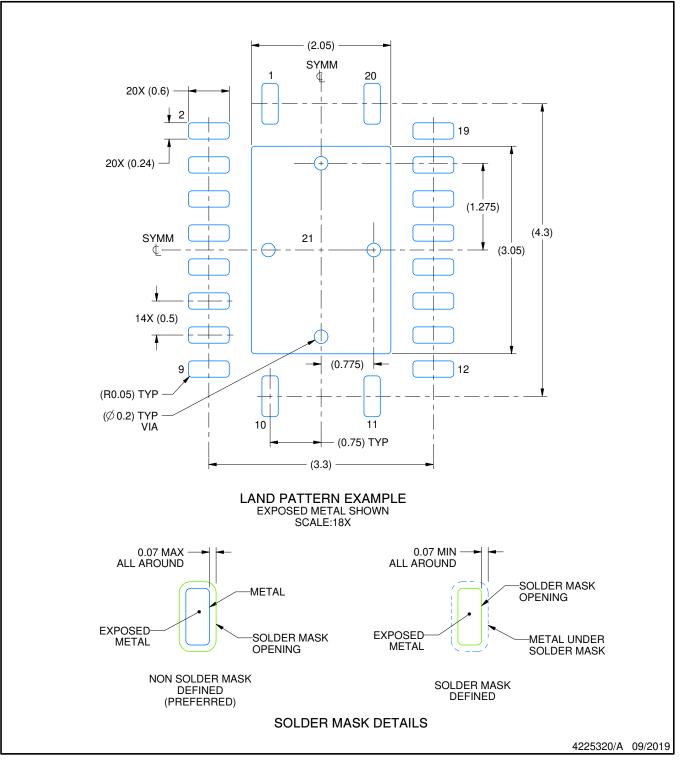


RGY0020A

EXAMPLE BOARD LAYOUT

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

 Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

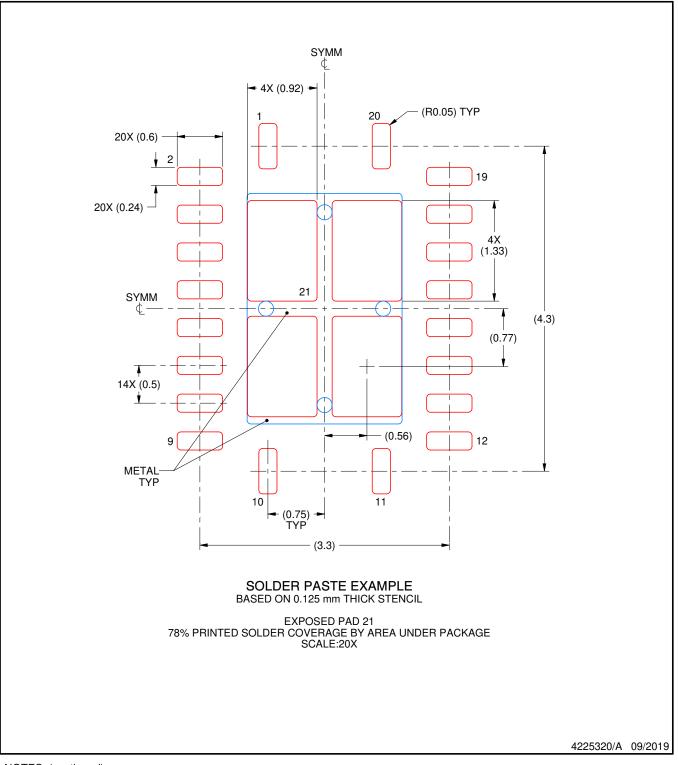


RGY0020A

EXAMPLE STENCIL DESIGN

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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